



PS7360-1A,PS7360L-1A

6-PIN DIP, HIGH ISOLATION VOLTAGE 600 V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7360-1A and PS7360L-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7360L-1A has a surface mount type lead.

FEATURES

- High isolation voltage (BV = 3 750 Vr.m.s.)
- 1 channel type (1 a output)
- Low LED operating current (IF = 2 mA)
- · Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- · Low offset voltage
- Ordering number of taping product: PS7360L-1A-E3, E4: 1 000 pcs/reel
- <R> <R>
- · Pb-Free product
- Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8252/8253
 - CSA approved: No. CA 101391
 - SEMKO approved: No. 606398
 - DEMKO approved: No. 309836
 - NEMKO approved: No. P00100964
 - FIMKO approved: No. FI 15188
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

APPLICATIONS

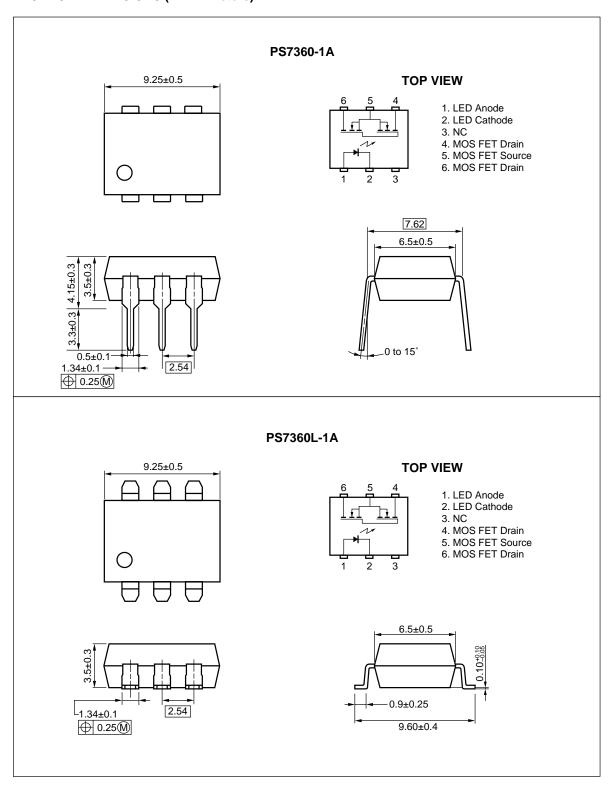
- · Exchange equipment
- · Measurement equipment
- FA/OA equipment

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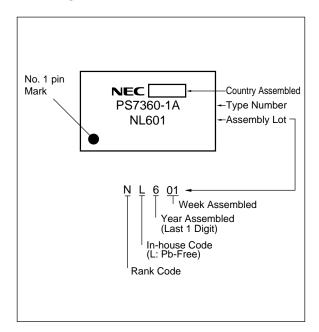
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PACKAGE DIMENSIONS (in millimeters)



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7360-1A	PS7360-1A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7360-1A
PS7360L-1A	PS7360L-1A-A			(UL, BSI, CSA, SEMKO,	
PS7360L-1A-E3	PS7360L-1A-E3-A		Embossed Tape 1 000 pcs/reel	DEMKO, NEMKO,	
PS7360L-1A-E4	PS7360L-1A-E4-A			FIMKO approved)	

^{*1} For the application of the Safety Standard, following part number should be used.

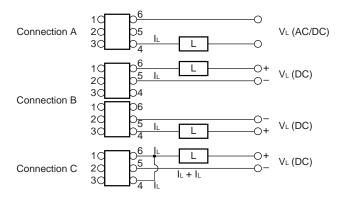
ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (De	C)	lf	50	mA
	Reverse Voltage		VR	5.0	V
	Power Dissipation		Po	50	mW
	Peak Forward Curre	ent *1	IFP	1	Α
MOS FET	Break Down Voltage		VL	600	V
	Continuous	Connection A	lι	90 (120)	mA
	Load Current *2	Connection B		130 (160)	
		Connection C		200 (210)	
	Pulse Load Current *3 (AC/DC Connection) Power Dissipation		ILP	250	mA
			Po	560	mW
Isolation Voltage *4			BV	3 750	Vr.m.s.
Total Power Dissipation			P⊤	610	mW
Operating Ambient Temperature			TA	-40 to +85	°C
Storage Temperature			T _{stg}	-40 to +125	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

Conditions: IF \geq 5 mA. Load current () value is.

The following types of load connections are available.



^{*3} PW = 100 ms, 1 shot

^{*2} Conditions: If ≥ 2 mA.

^{*4} AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output Pins 1-3 shorted together, 4-6 shorted together.

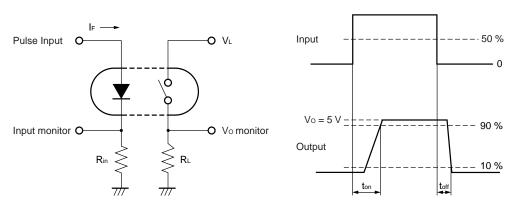
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lf	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

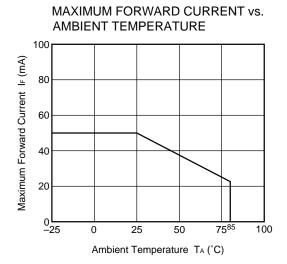
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lr	V _R = 5 V			5.0	μΑ
MOS FET	Off-state Leakage Current	Loff	V _D = 600 V		0.03	1.0	μА
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		110		pF
Coupled	LED On-state Current	IFon	I _L = 90 mA			2.0	mA
	On-state Resistance	R _{on1}	I _F = 10 mA, I _L = 10 mA		41	50	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 90 \text{ mA}, t \le 10 \text{ ms}$		33	45	
	Turn-on Time *1, 2	ton	If = 10 mA, Vo = 5 V, R _L = 2 k Ω ,		0.6	2.0	ms
	Turn-off Time *1, 2	toff	PW ≥ 10 ms		0.03	0.2	
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF

*1 Test Circuit for Switching Time

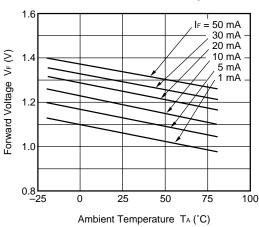


<R> *2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

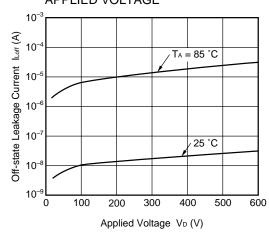
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)



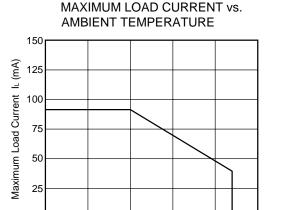




OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



Remark The graphs indicate nominal characteristics.



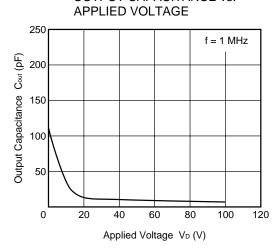
Ambient Temperature T_A (°C)

OUTPUT CAPACITANCE vs.

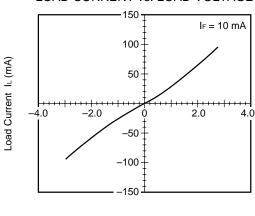
75 ⁸⁵

100

0**∟** -25

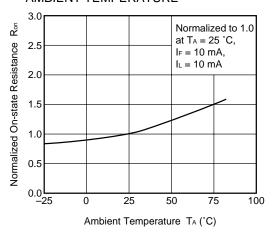


LOAD CURRENT vs. LOAD VOLTAGE

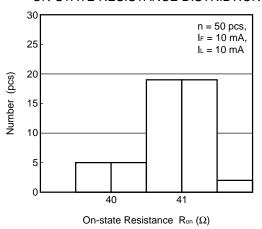


Load Voltage V_L (V)

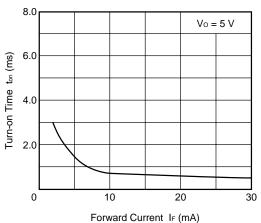
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



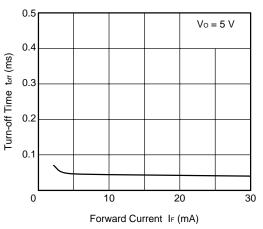
ON-STATE RESISTANCE DISTRIBTION



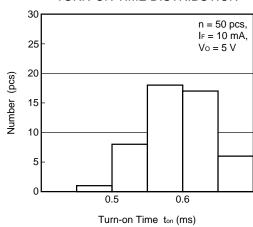
TURN-ON TIME vs. FORWARD CURRENT



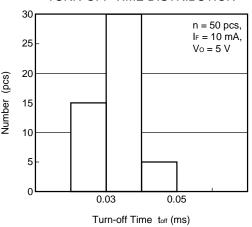
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

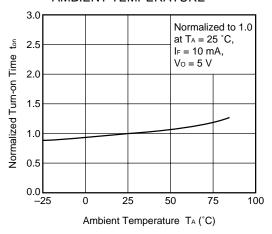


TURN-OFF TIME DISTRIBUTION



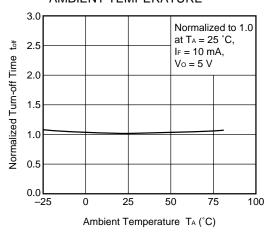
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

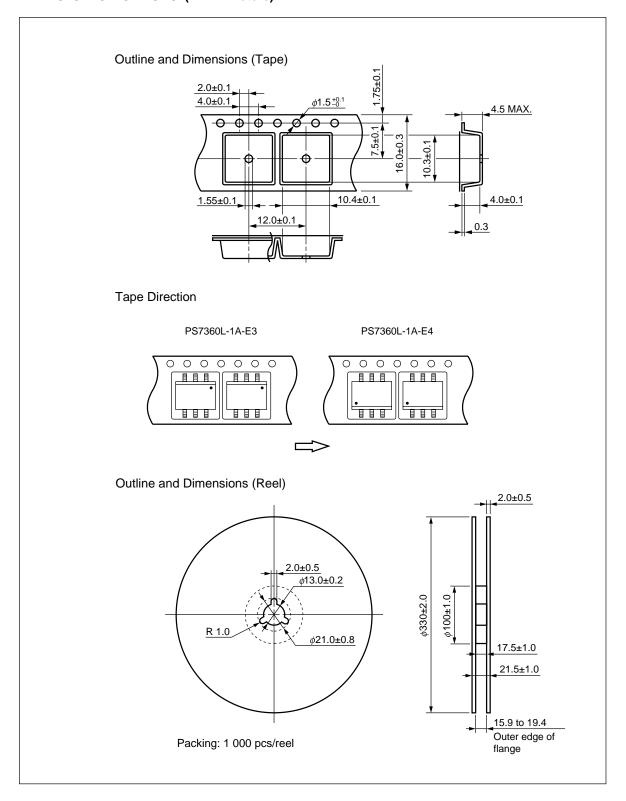


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

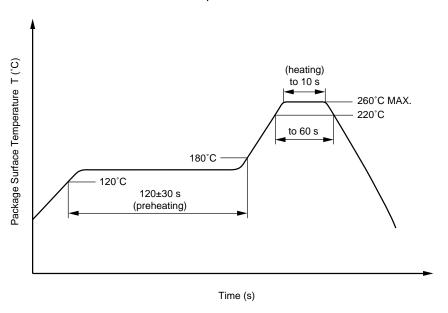
Time of peak reflow temperature
 Time of temperature higher than 220°C
 50 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Two

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- <R>
- To avoid quality degradation, assembling within 1 month after take this device out from covered pack is required. (Storage conditions 25°C, 65%RH MAX.)
- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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